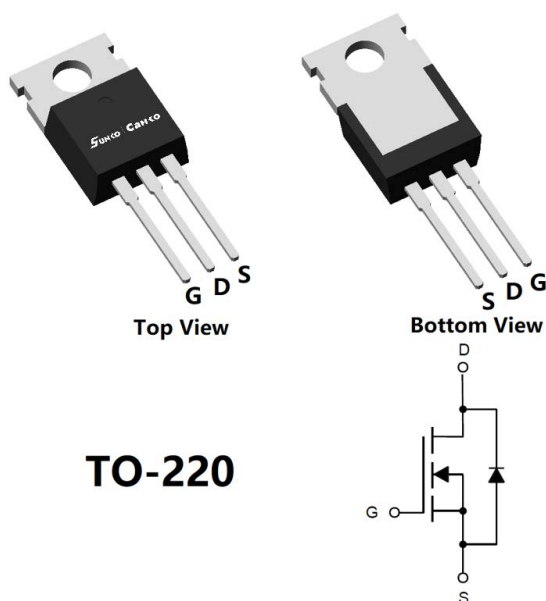


N-Channel Enhancement Mode Field Effect Transistor



Product Summary

- V_{DS} 60V
- I_D 200A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) $<2.9\text{ mohm}$
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) $<3.6\text{ mohm}$
- 100% EAS Tested
- 100% ∇V_{DS} Tested

General Description

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- Consumer electronic power supply
- Isolated DC-DC Converters
- Motor control
- Invertors

■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	60	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current ^A	$T_C=25^\circ\text{C}$	I_D	200	A
	$T_C=100^\circ\text{C}$		125	
Pulsed Drain Current ^B		I_{DM}	600	A
Avalanche energy ^C		EAS	500	mJ
Total Power Dissipation ^D		P_D	260	W
Thermal Resistance Junction-to-Case		$R_{\theta JC}$	0.48	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Ambient ^E		$R_{\theta JA}$	28	
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	$^\circ\text{C}$

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SCP200G06A	B1	SCP200G06A	50	/	5000	Tube

SCP200G06A

■ Electrical Characteristics (T_j=25℃ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	1.2	1.6	2.2	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} = 10V, I _D =20A		2.35	2.9	mΩ
		V _{GS} = 4.5V, I _D =15A		2.9	3.6	
Diode Forward Voltage	V _{SD}	I _S =20A,V _{GS} =0V			1.2	V
Maximum Body-Diode Continuous Current	I _S				200	A
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =25V,V _{GS} =0V,f=100KHZ		5950		pF
Output Capacitance	C _{oss}			1250		
Reverse Transfer Capacitance	C _{rss}			85		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =10V,V _{DS} =50V,I _D =50A		93		nC
Gate-Source Charge	Q _{gs}			17		
Gate-Drain Charge	Q _{gd}			14		
Reverse Recovery Chrage	Q _{rr}	I _F =25A, di/dt=100A/us		73		
Reverse Recovery Time	t _{rr}			68		
Turn-on Delay Time	t _{d(on)}	V _{GS} =10V,V _{DD} =30V,I _D =25A R _{GEN} =2Ω		22.5		ns
Turn-on Rise Time	t _r			6.7		
Turn-off Delay Time	t _{d(off)}			80.3		
Turn-off fall Time	t _f			26.9		

Note:

- The maximum current rating is package limited.
- Repetitive rating; pulse width limited by max. junction temperature.
- V_{DD}=50 V, R_G=25 Ω, L=0.5mH, starting T_j=25 °C.
- P_D is based on max. junction temperature, using junction-case thermal resistance.
- The value of R_{θJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with Ta=25 °C.

■ Typical Performance Characteristics

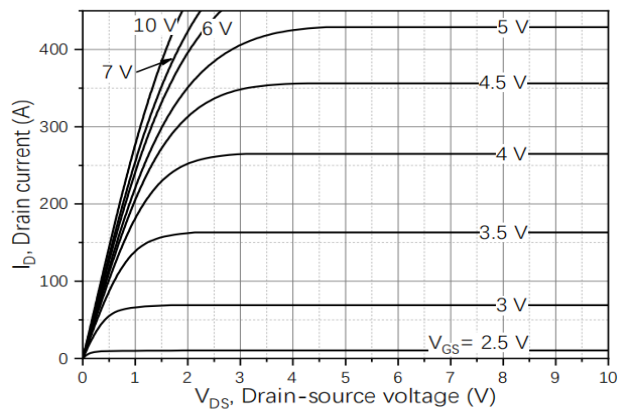


Figure1. Output Characteristics

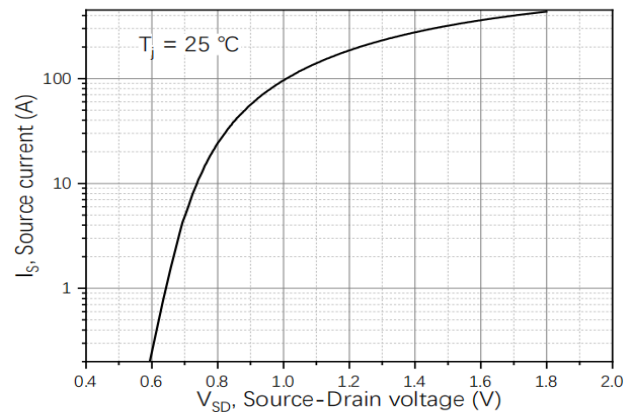


Figure2. Transfer Characteristics

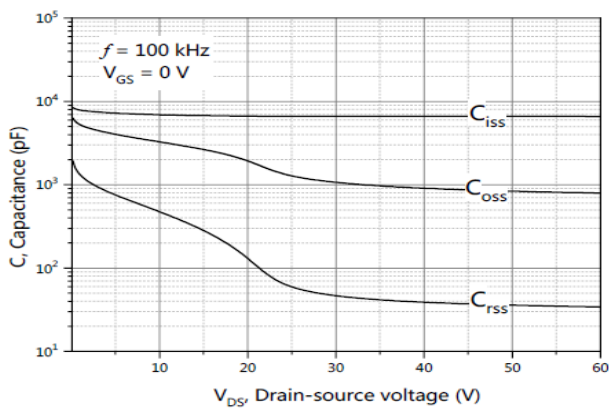


Figure3. Capacitance Characteristics

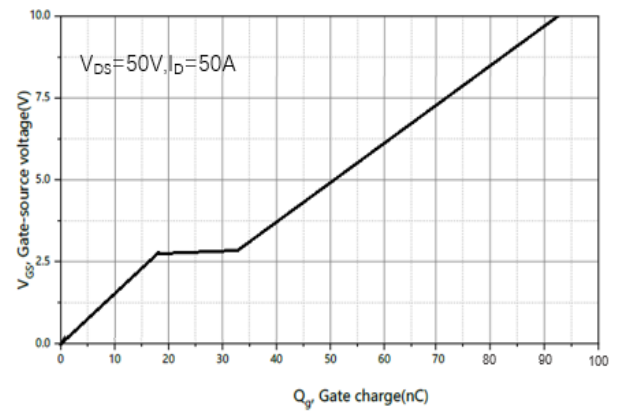


Figure4. Gate Charge

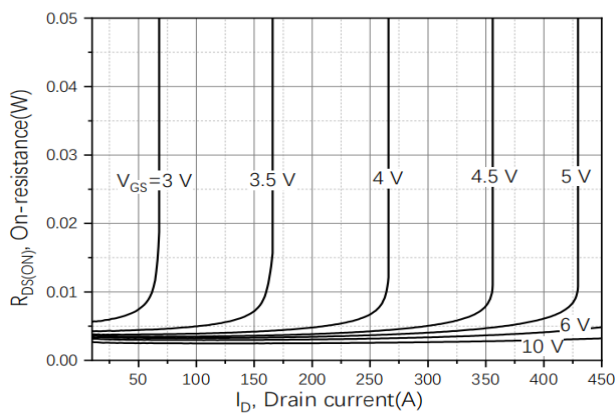


Figure5. Drain-Source on Resistance

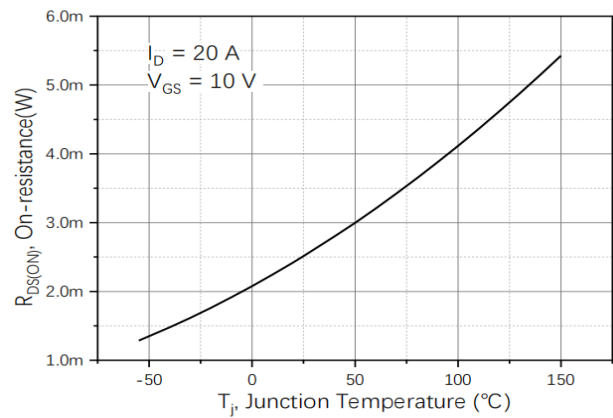


Figure6. Drain-Source on Resistance

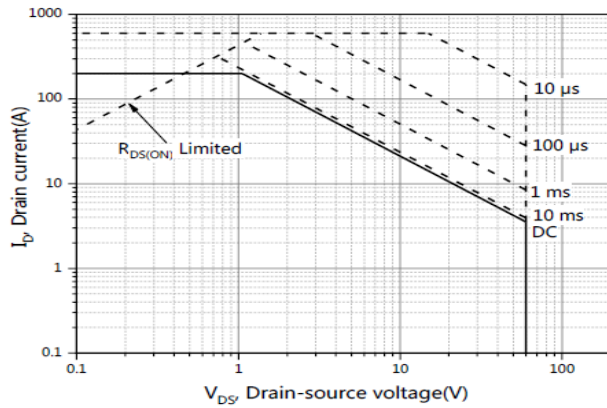


Figure7. Safe Operation Area

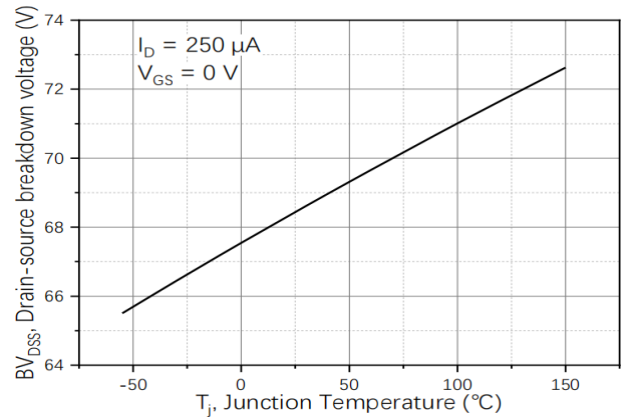


Figure8. Drain-source breakdown voltage

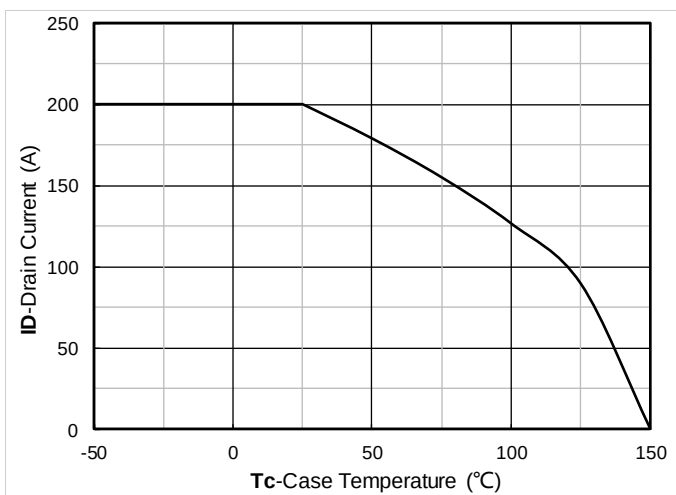


Figure 9. Current dissipation

■ Test circuits and waveforms

Figure A: Gate Charge Test Circuit & Waveforms

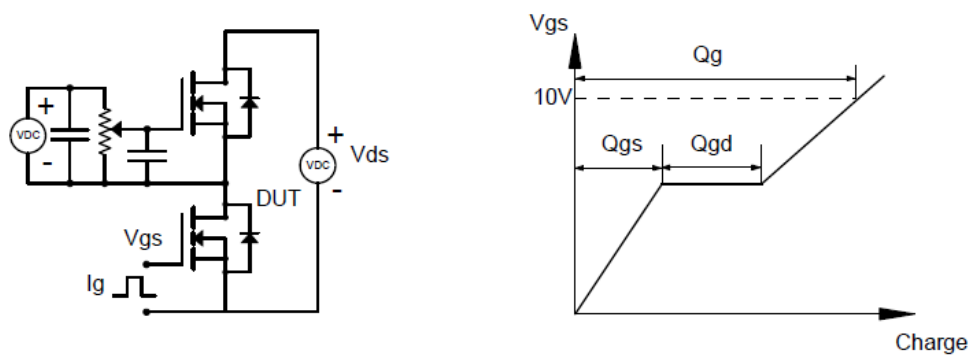


Figure B: Resistive Switching Test Circuit & Waveforms

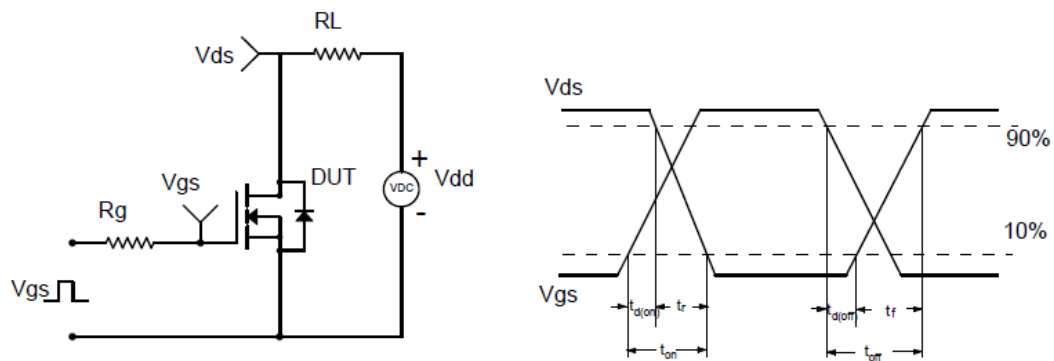


Figure C: Unclamped Inductive Switching (UIS) Test

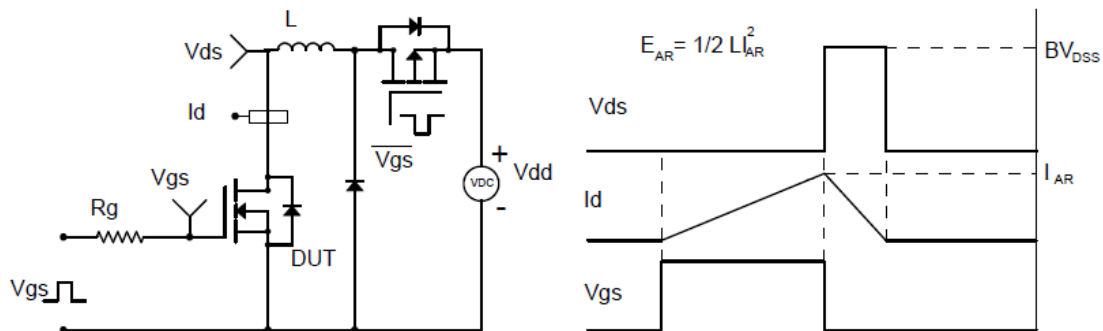
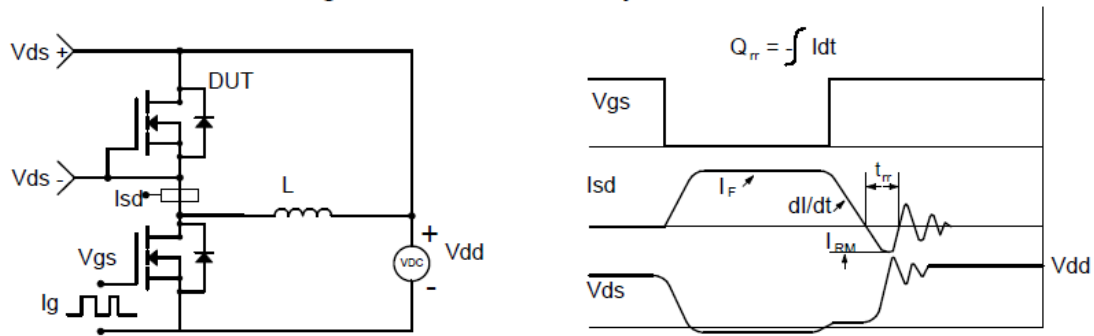
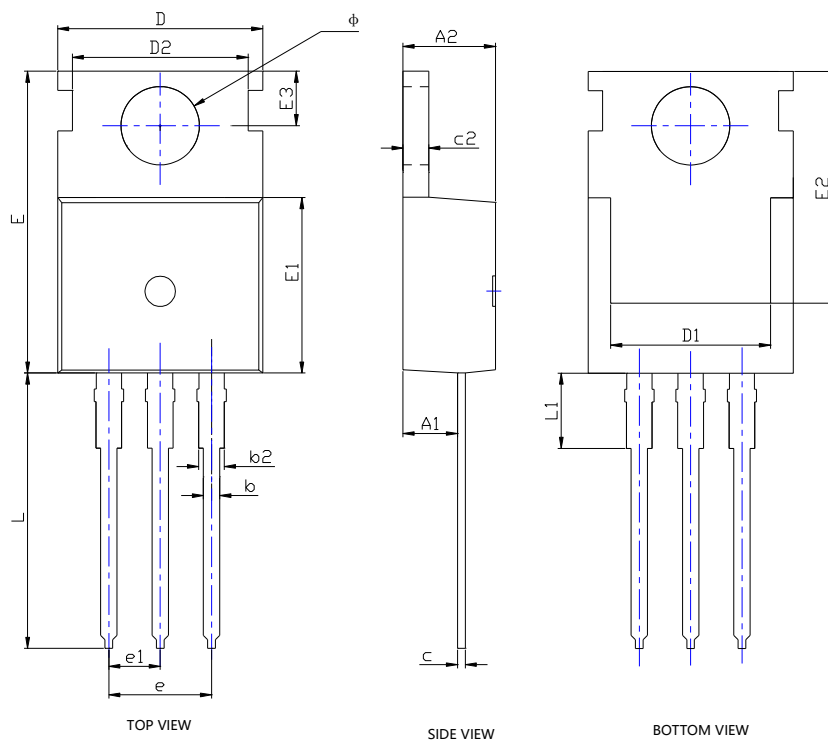


Figure D: Diode Recovery Test Circuit & Waveforms



■ TO-220AB-C Package Information



SYMBOL	DIMENSIONS			
	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A1	0.091	0.098	2.300	2.500
A2	0.173	0.181	4.400	4.600
b	0.028	0.035	0.700	0.900
b2	0.049	0.056	1.250	1.420
c	0.018	0.022	0.450	0.550
c2	0.049	0.053	1.250	1.350
D	0.382	0.402	9.700	10.200
D1	0.295	0.331	7.500	8.400
D2	0.335	0.350	8.500	8.900
E	0.602	0.634	15.300	16.100
E1	0.358	0.366	9.100	9.300
E2	0.497	0.525	12.630	13.330
E3	0.108BSC		2.750BSC	
e	0.200BSC		5.080BSC	
e1	0.100BSC		2.540BSC	
L	0.512	0.531	13.000	13.500
L1	---	0.138	---	3.500
ø	0.140	0.148	3.550	3.750

NOTE:
1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
2. TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.

Disclaimer

The information presented in this document is for reference only. Shanghai Sunco Electronics Co., Ltd reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Russiansunco or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

This publication supersedes & replaces all information previously supplied. For additional information, please visit our website [http:// www.russiansunco.com](http://www.russiansunco.com) or consult your nearest Russiansunco's sales office for further assistance.